

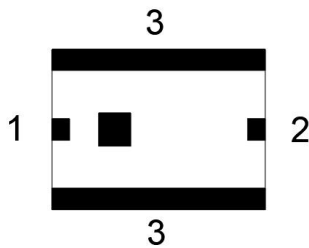
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

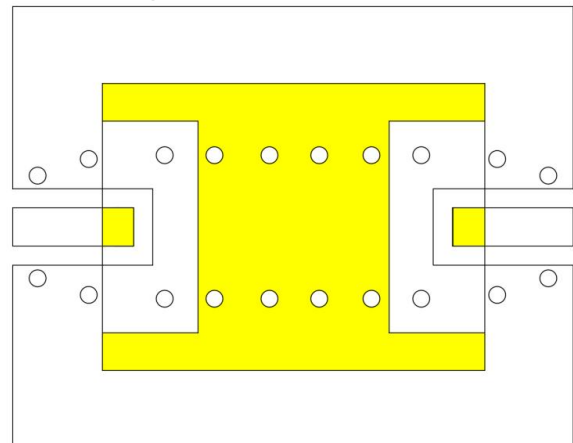
NO.	Parameter	Frequency (MHz)	SPEC		
			Min.	Typ.	Max.
1	Insertion Loss (dB) @25°C	2338~2413			4.0
2	Ripple(dB)	2338~2413			1.0
3	VSWR	2338~2413			2.0
4	Attenuation (dB)	2188	25		
		2488	10		

Construction



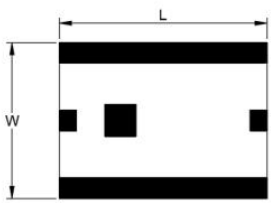
PIN	Connection
1	Input Port
2	Output Port
3	GND

Mounting Considerations

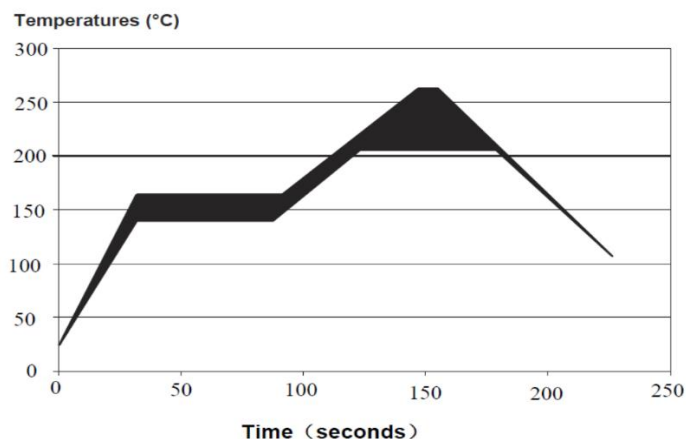


Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

Dimensions

Figure	Symbol	Dimension (mm)
Top View  Side View  Bottom View 	L	6.00 ± 0.20
	W	4.50 ± 0.20
	T	2.00 max.
	A	0.60 ± 0.15
	B	3.32 ± 0.15
	C	1.50 ± 0.15
	D	0.50 ± 0.15

Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.

Yantel Corporation

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For detailed performance specs & shopping online see Yantel web site : www.yantel-corp.com